

## ANGI053059-P53

### **C-band matched GaN Device**

#### **Features:**

Frequency: 5.3~5.9GHz

Saturated Output Power: Psat≥53dBm

PowerGain: Gain≥10dB Add-Efficiency: PAE≥45% Port Matching: Zin/Zout=50Ω

### **Description:**

ANGI053059-P53 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 5.3~5.9GHz. This device can be used in different RF/Microwave system and subsystem.

The high output power level, high efficiency and wide operating temperature range can make application very flexible.

# Maximun Ratings (TC=25°C, Not recommended working under this condition):

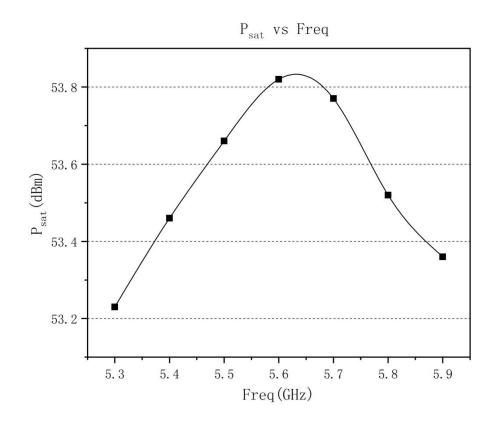
|                                      | Symbol           | Value       | Unit |
|--------------------------------------|------------------|-------------|------|
| Voltage between source and drain     | <b>V</b> DS      | 40          | V    |
| Voltage between gate and source      | V <sub>G</sub> s | -5          | V    |
| Storage Temperature Range            | $T_{stg}$        | -65 to +175 | °C   |
| Drain and Source Channel Temperature | Tch              | 175         | °C   |



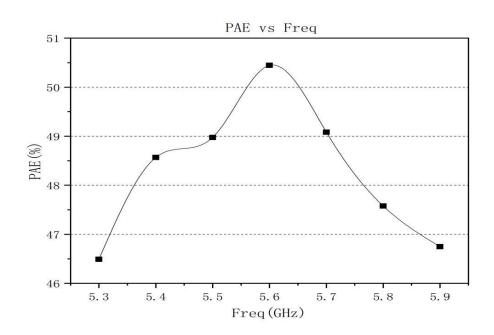
## **Electrical Characteristics:**

|                        |                 |                  |      | Value |      |      |
|------------------------|-----------------|------------------|------|-------|------|------|
|                        | Symbol          | Test condition   | Min  | Тур   | Max  | Unit |
| Drain Current Idsr     |                 | -                | 14   | -     | А    |      |
| Saturated Output Power | Psat            | Vds=28V PW.      | 53   | -     | -    | dBm  |
| Gain                   | n Gp Pin: 43dBm | 10               | -    | -     | dB   |      |
| Add-Efficiency         | PAE             | Freq: 5.3~5.9GHz | 45   | -     | -    | %    |
| Gain Flatness          | ΔG              |                  | -0.8 | -     | +0.8 | dB   |

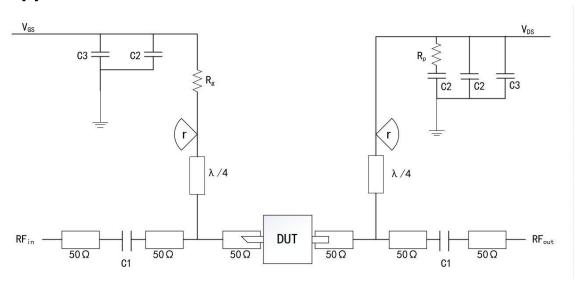
# **Typical Curve:**



## **Internal Matching GaN Device**



## **Application Circuit:**



DUT: Device to be tested

C1:4.7pF  $R_p$ :51 $\Omega$ 

C2:1000pF  $R_G:15\Omega$ 

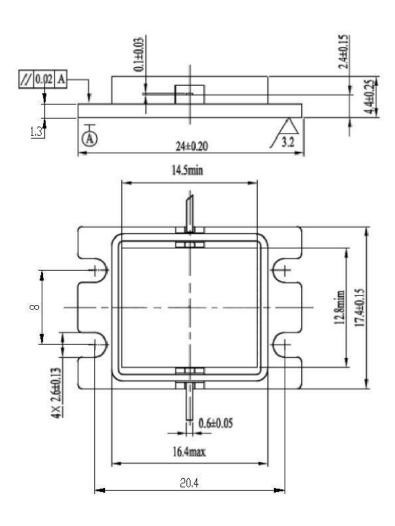
C3:100uF r(radius)≈5.8mm(Rogers5880, 20mil)



#### **ESD Level:**

| ESD | Class III | 2000V |
|-----|-----------|-------|
|     |           |       |

## **Outline:**



### **Precautions for use:**

- Pay attention to drying transportation and storage.
- Pay attention to anti-static during chip use and assembly, and wear grounding anti-static bracelet.
- When powering up, first apply grid power then add leakage.